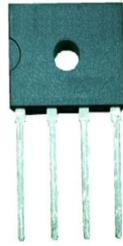


## 2.0A Single-Phase Glass Passivated Bridge Rectifiers

Recifier Reverse Voltage 50V to 1000V



**D3K**

### Features

- Glass passivated junction
- The plastic material used carries Underwriters Laboratory flammability recognition 94V-0
- Suge overload ratings to 80 amperes peak
- Ideal for printed circuit board application
- Solder dip 275 °C max. 7 s, per JESD 22-B106

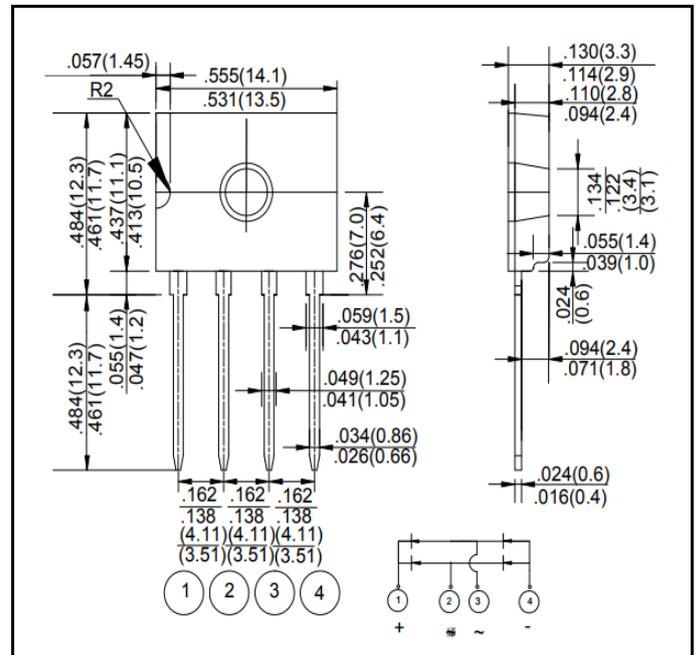
### Mechanical Data

Case:Molded plastic

Terminals: Tin plated leads, solderable per  
J-STD-002 and JESD22-B102

Polarity:Polarity symbols molded or Marked on body

Mounting Position:Any



### Maximum Ratings & Thermal Characteristics

Dimensions in inches and (millimeters)

Rating at 25°C ambient temperature unless otherwise specified, Resistive or inductive load, 60HZ.

For Capacitive load derate current by 20%

Parameter	Symbol	D2UB05	D2UB10	D2UB20	D2UB40	D2UB60	D2UB80	D2UB100	unit
Maximum repetitive peak reverse voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS bridge input voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	VDC	50	100	200	400	600	800	1000	V
Average rectified output current @60Hz sine wave, R-load	With heatsink Tc =140°C	2.0							A
	Without heatsink Ta =29°C	1.2							
Peak forward surge current single sine-wave superimposed on rated load (JEDEC Method)	IFSM	80							A
Rating for fusing(t<8.3ms)	I <sup>2</sup> t	33							A <sup>2</sup> sec
Maximum instantaneous forward voltage drop per leg at 1.2A	VF	1.05							V
Typical thermal resistance to ambient (without heatsink)	R <sub>θJA</sub>	37							°C/w
Typical thermal resistance to case (with heatsink)(Note1)	R <sub>θJC</sub>	1.5							°C/w
Typical thermal resistance to lead (without heatsink)	R <sub>θJL</sub>	5.5							°C/w
Mounting torque(Suggests 045~0.65)	Tor	Rating Torque:0.8(Suggests 045~0.65)							N.m
Maximum DC reverse current at rated @T <sub>J</sub> =25°C	IR	5							μA
DC blocking voltage per element @T <sub>J</sub> =125°C		500							
Operating junction temperature range	T <sub>J</sub>	-55to+150							°C
Storage temperature range	TSTG	-55to+150							°C

Notes: (1) Device mounted on 50mm\*50mm\*1.6mm Cu plate heatsink.

(2) The typical data above is for reference only

## Rating and Characteristic Curves (TA=25°C Unless otherwise noted)

FIG.1-DERATING CURVE FOR

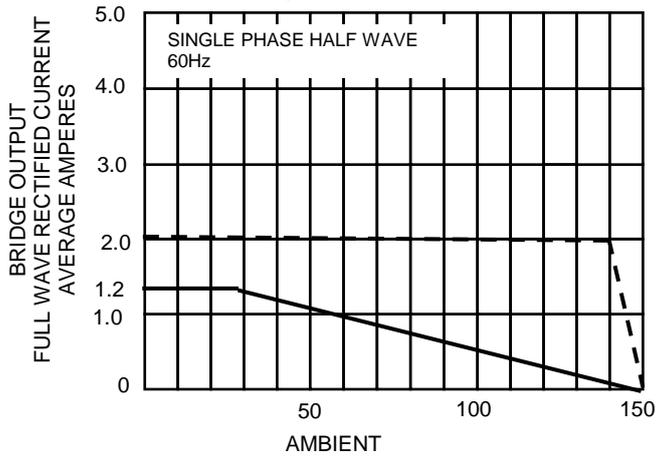


FIG.2-MAXIMUM NON-REPETITIVE SURNGE CURRENT

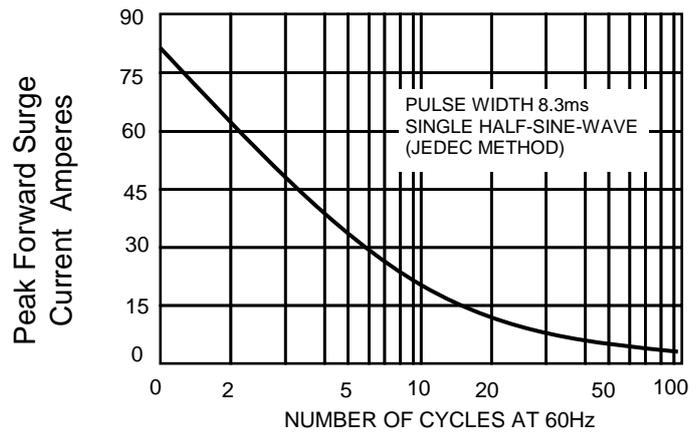


FIG.3-TYPICAL REVERSE CHARACTERISTICS

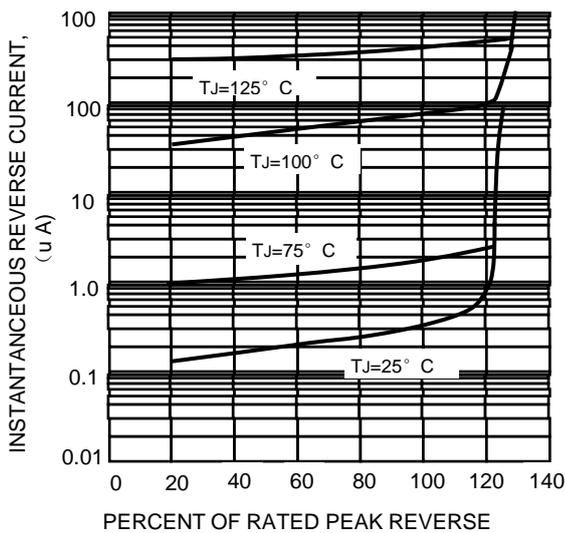


FIG.4-TYPICAL FORWARD CHARACTERISTICS

